20 April 2004

L Number	Hits	Search Text	DB	Time stamp
_	1571	204/\$.ccls. and (wafer or semiconductor) and seal	USPAT;	2004/04/20
		•	US-PGPUB;	08:59
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	531	(204/198,232,237,242,275.1,297.01,297.06,297.14.ccl	S.USPAT;	2003/10/27
		204/224r,224m.ccls.) and (wafer or semiconductor)	US-PGPUB;	08:46
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	218	((204/198,232,237,242,275.1,297.01,297.06,297.14.cc		2003/10/27
		204/224r,224m.ccls.) and (wafer or semiconductor))	US-PGPUB;	10:30
		and seal	EPO; JPO;	
		4.14.4.4.1	DERWENT;	
			IBM_TDB	
_	60	(204/198,232,237,242,275.1,297.01,297.06,297.14.ccl	_	2003/10/27
		204/224r,224m.ccls.) and sponge	US-PGPUB;	09:18
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	2	6176992.pn.	USPAT;	2003/10/27
	_	017 077 I.p.i.	US-PGPUB;	09:25
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	14	("3595089" "4610772" "5024735" "5171412"	USPAT	2003/10/27
		"5429733" "5558568" "5692947" "5755859"		09:26
		"5807165" "5833820" "5863412" "5930669"		
		"5933753" "6004880").PN.		
_	2	6228233.pn.	USPAT;	2003/10/27
	-	occoso.pn.	US-PGPUB;	09:33
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
	2	4807973.pn.	USPAT;	2003/10/27
		1007 27 0.pm.	US-PGPUB;	09:33
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	23	(204/\$.ccls. or 205/\$.ccls.) and datta.in.	USPAT;	2003/10/27
		(ab it wilders of about wilders, and additions.	US-PGPUB;	10:33
			EPO; JPO;	
-			DERWENT;	
			IBM_TDB	
	3838	204/198,232,237,242,275.1,297.01,297.06,297.14.ccls		2003/10/27
-	3038	204/224r,224m.ccls.	US-PGPUB;	10:53
		EO 17 EETI /EETIII.OOI3.	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
	L		TRW_IDR	J

	313	(204/198,232,237,242,275.1,297.01,297.06,297.14.ccl	USPAT;	2003/10/27
_	0.0	204/224r,224m.ccls.) and (temperature with (anode	US-PGPUB;	10:54
		or cathode or electrode))	EPO; JPO;	
		, 52,52 5. 5.65527,	DERWENT;	
			IBM_TDB	
	67	(204/198,232,237,242,275.1,297.01,297.06,297.14.ccl		2003/10/27
	٠, ا	204/224r,224m.ccls.) and (temperature near2 (anode	US-PGPUB;	11:03
		or cathode or electrode))	EPO; JPO;	
		, oa,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	DERWENT;	
			IBM_TDB	
_	10	3859196.URPN.	USPAT	2003/10/27 11:01
	30	(204/198,232,237,242,275.1,297.01,297.06,297.14.ccl	s.USPAT;	2003/10/27 11:13
		204/224r,224m.ccls.) and ((temperature near2	US-PGPUB;	
		control\$5) with (anode or cathode or electrode))	EPO; JPO;	
,		Common (amount of common o	DERWENT;	
			IBM_TDB	
1_	2	("5507923" "6017437").PN.	USPAT	2003/10/27
	_	(0007) _ 0		11:06
_	25	(204/198,232,237,242,275.1,297.01,297.06,297.14.ccl	s.USPAT;	2003/10/27 11:19
		204/224r,224m.ccls.) and ((coolant or (cooling adj	US-PGPUB;	
		(fluid or liquid))) with (anode or cathode or	EPO; JPO;	
		electrode))	DERWENT;	
			IBM_TDB	
_	531	(204/198,232,237,242,275.1,297.01,297.06,297.14.ccl	.USPAT;	2003/10/27
		204/224r,224m.ccls.) and (wafer or semiconductor)	US-PGPUB;	11:20
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	375	((204/198,232,237,242,275.1,297.01,297.06,297.14.cc		2003/10/27
		204/224r,224m.ccls.) and (wafer or semiconductor))	US-PGPUB;	11:22
		and (coolant or (cooling fluid) or heat or heating)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	176	((204/198,232,237,242,275.1,297.01,297.06,297.14.cc		2003/10/27
		204/224r,224m.ccls.) and (wafer or semiconductor))	US-PGPUB;	11:22
1		and ((coolant or (cooling fluid) or heat or heating)	EPO; JPO;	
		with (anode or cahode or electrode))	DERWENT;	
		((004,400,000,007,040,0754,007,04,007,04,007,44,007,04,007,04,007,44,007,007	IBM_TDB	2003/10/27 11:21
-	93	((204/198,232,237,242,275.1,297.01,297.06,297.14.cc	US-PGPUB;	2003/10/2/ 11.21
		204/224r,224m.ccls.) and (wafer or semiconductor))	EPO; JPO;	
		and ((coolant or (cooling fluid) or heat or heating)	DERWENT;	
		near3 (anode or cahode or electrode))	IBM_TDB	
	9	((204/198,232,237,242,275.1,297.01,297.06,297.14.cc		2003/10/27 11:21
-		204/224r,224m.ccls.) and (wafer or semiconductor))	US-PGPUB;	3000,10,2,11,61
		and ((coolant or (cooling adj fluid) or heat or heating)	EPO; JPO;	
		near3 (anode or cahode or electrode))	DERWENT;	
		(3.1.2.2.2.2.2.2.2.2.2.2.2.2.2.2.2.2.2.2.	IBM_TDB	
_	197	((204/198,232,237,242,275.1,297.01,297.06,297.14.co		2003/10/27
		204/224r,224m.ccls.) and (wafer or semiconductor))	US-PGPUB;	11:22
		and (coolant or (cooling adj fluid) or heat or heating)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	

	32	((204/198,232,237,242,275.1,297.01,297.06,297.14.cc	sUSPAT;	2003/10/27
	"	204/224r,224m.ccls.) and (wafer or semiconductor))	US-PGPUB;	11:22
		and ((coolant or (cooling adj fluid) or heat or heating)	EPO; JPO;	
		with (anode or cahode or electrode))	DERWENT;	
		With (dilede of canode of block one))	IBM TDB	
	2	("5507923" "6017437").PN.	USPAT	2003/10/27
-	i - 1	(3307)23 3017 (37)		11:27
	o	868577.apn.	USPAT;	2003/10/27
-	0	000577 :арп.	US-PGPUB;	11:42
			EPO: JPO:	
			DERWENT:	
			IBM_TDB	
	22	(U5-6077412-\$ or U5-6017437-\$ or US-5951833-\$	USPAT;	2003/10/27
-	22	•	US-PGPUB	11:50
		or US-5567300-\$ or US-5776330-\$ or	03-10106	11.50
		US-6176992-\$ or US-6228233-\$ or US-6251235-\$		
		or US-6258240-\$ or US-6261433-\$ or		
		US-6270647-\$ or US-6328872-\$ or US-6334937-\$		
		or US-6103096-\$ or US-5284554-\$ or		
		US-3859196-\$ or US-6398926-\$ or US-5228966-\$		
		or US-5198083-\$ or US-3894925-\$ or		
		US-3637468-\$).did. or (US-20020056647-\$).did.		0000 40 67 44 54
-	8	((US-6077412-\$ or US-6017437-\$ or US-5951833-\$	USPAT;	2003/10/27 11:51
		or US-5567300-\$ or US-5776330-\$ or	US-PGPUB;	
		US-6176992-\$ or US-6228233-\$ or US-6251235-\$	EPO; JPO;	
		or US-6258240-\$ or US-6261433-\$ or	DERWENT;	
		US-6270647-\$ or US-6328872-\$ or US-6334937-\$	IBW_TDB	
		or US-6103096-\$ or US-5284554-\$ or		
İ		US-3859196-\$ or US-6398926-\$ or US-5228966-\$		
		or US-5198083-\$ or US-3894925-\$ or		
		US-3637468-\$).did. or (US-20020056647-\$).did.)		
		and ((electrolyte or solution or fluid) with		
		(temperature or cool\$4 or heat\$4))		
-	7	((US-6077412-\$ or US-6017437-\$ or US-5951833-\$	USPAT;	2003/10/27
		or US-5567300-\$ or US-5776330-\$ or	US-PGPUB;	12:32
		US-6176992-\$ or US-6228233-\$ or US-6251235-\$	EPO; JPO;	,
		or US-6258240-\$ or US-6261433-\$ or	DERWENT;	
		US-6270647-\$ or US-6328872-\$ or US-6334937-\$	IBW_TDB	
		or US-6103096-\$ or US-5284554-\$ or		
		US-3859196-\$ or US-6398926-\$ or US-5228966-\$		
		or US-5198083-\$ or US-3894925-\$ or		
		US-3637468-\$).did. or (US-20020056647-\$).did.)		
		and (dc or (direct adj current))		
_	0	868577.apn.	USPAT;	2004/04/20
1		·	US-PGPUB;	08:59
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	2655	204/198,232,237,242,275.1,297.01,297.06,297.14.ccls		2004/04/20
			US-PGPUB;	09:50
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
L	L	1.		

<u>-</u>	68	204/198,232,237,242,275.1,297.01,297.06,297.14.ccls	USPAT;	2004/04/20
		and (ammeter or (current near (detect\$4 or sensor	US-PGPUB;	10:01
		or sense or sensing or sensed)))	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	1521	204/224r,224m.ccls.	USPAT;	2004/04/20
		· ·	US-PGPUB;	10:01
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	47	204/224r,224m.ccls. and (ammeter or (current near	USPAT;	2004/04/20
		(detect\$4 or sensor or sense or sensing or sensed)))	US-PGPUB;	10:16
		,	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	42	(204/224r,224m.ccls. and (ammeter or (current near	USPAT;	2004/04/20
		(detect\$4 or sensor or sense or sensing or sensed))))	US-PGPUB;	10:03
		not	EPO; JPO;	
		(204/198,232,237,242,275.1,297.01,297.06,297.14.ccl	DERWENT;	
		and (ammeter or (current near (detect\$4 or sensor	IBW_TDB	
•	1	or sense or sensing or sensed))))		
-	1686	205/118,122,125.ccls.	USPAT;	2004/04/20
:			US-PGPUB;	10:04
			EPO; JPO;	
			DERWENT;	
			IBW_TDB	
-	17	205/118,122,125.ccls. and (ammeter or (current near	USPAT;	2004/04/20
		(detect\$4 or sensor or sense or sensing or sensed)))	US-PGPUB;	10:04
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	